

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	NUNC PRO TUNC ASSIGNMENT
EFFECTIVE DATE:	07/15/2002

CONVEYING PARTY DATA

Name	Execution Date
Chun Ho Fan	07/15/2002
Tsui Yee Lin	07/15/2002
Kin Pui Kwan	07/15/2002
Shui Ming Tse	07/15/2002
Wing Him Lau	07/15/2002
Shuk Man Wong	07/15/2002

RECEIVING PARTY DATA

Name:	ASAT Limited
Street Address:	138 Texaco Road
Internal Address:	QPL Industrial Building
City:	Tsuen Wan, N.T.
State/Country:	HONG KONG

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	7449771

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	2001410
NAME OF SUBMITTER:	Mitchell M. Wong
Total Attachments: 3 source=044_Assignment#page1.tif source=044_Assignment#page2.tif source=044_Assignment#page3.tif	

WORLDWIDE ASSIGNMENT

WHEREAS, WE, **Chun Ho FAN; Tsui Yee LIN; Kin Pui KWAN; Shui Ming, TSE; Wing Him LAU; and Shuk Man, WONG** residing at, respectively, Flt E, 27/F, Blk 3, Lido Garden, Sham Tseng, (HK); Rm 1510, Yiu Tung Hse, Tung Tau Est, Kowloon, (HK); Flat F, 9/F, Blk 1, Highland Park, Lai Kong Street, N.T., Hong Kong; 5/F, 34 Shing On Street, Sai Wan Ho, Hong Kong; 18 Golden Bamboo Road E., Fairview Park, Yuen Long, N.T., Hong Kong; and B7, 14/F, Fuk Ming Building, Fuk Tsun Street, Tai Kok, KLN, Hong Kong, have invented certain new and useful improvements in an invention entitled **MULTIPLE LEADFRAME LAMINATED IC PACKAGE** for which an application for United States Letters Patent will be filed; and

WHEREAS, **ASAT LTD.**, a company organized and existing under the laws of the city of Hong Kong, having a place of business at QPL Industrial Building, 14th Floor, 138 Texaco Road, Tsuen Wan, New Territories Hong Kong is desirous of acquiring the full and exclusive right, title and interest in and to said application inclusive of any and all priority rights derived therefrom and the inventions therein disclosed, and in and to all Letters Patent, both United States and foreign, to be granted for said inventions;

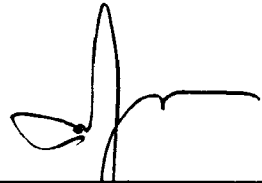
NOW, THEREFORE, for a valuable consideration, the receipt whereof is hereby acknowledged, WE, do hereby sell, assign, transfer, and set over unto the said Assignor, its successors and assigns, the full and exclusive right, title and interest in and to the aforesaid application for United States Letters Patent inclusive of any and all priority rights derived therefrom, and the invention therein disclosed, and in and to all Letters Patent and issues thereof which may be granted upon said application and in and to all Letters Patent which may be issued upon any substitutes, divisions, or continuations of said application, and in and to any and all Letters Patent which may be granted for said inventions in any foreign country or countries; the same to be held and enjoyed by the said Assignor for its own use and behoof, and for the use and behoof of its successors and assigns, to the full end of the term or terms for which said Letters Patent and reissues thereof may be granted as fully and entirely as the same would have been held and enjoyed by them had this assignment and sale not been made;

AND WE, hereby agree to execute, upon request, any and all further papers which may be necessary or desirable to enable the said Assignor, its successors and assigns, to file and prosecute said application, and any and all substitutes, divisions, or continuations thereof, and any and all reissues of the Letters Patent granted upon said application, or upon any substitutes, divisions, or continuations thereof, and any and all applications for foreign Letters Patent on said invention; and WE, further agree to execute any and all further papers which may be necessary or desirable to vest or perfect the title of said Assignor, its successors and assigns, in and to said application and the inventions therein disclosed, and in and to any and all Letters Patent and reissues thereof, both United States and foreign, which may be granted upon said application, and any substitutes, divisions, or continuations thereof, and upon any foreign applications.

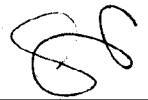
AND WE, hereby authorize and request The Commissioner of Patents to issue each and every Letters Patent to be granted upon the aforesaid application for United States Letters Patent, and upon any and all substitutes, divisions, and continuations of said application, and each and every reissue of said Letters Patent, to the said Assignor, its successors and assigns, as the assignee of the entire right, title and interest therein, in accordance with this assignment.

WITNESS my hand at HONG KONG

this 15 day of JULY, 2002



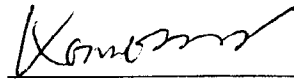
Chun Ho FAN

Witness: 



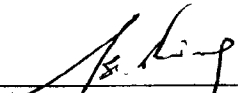
Tsui Yee LIN

Witness: 



Kin Pui KWAN

Witness:





Shui Ming, TSE

Witness:




Wing Him LAU

Witness:




Shuk Man WONG

Witness: